

PRESS RELEASE

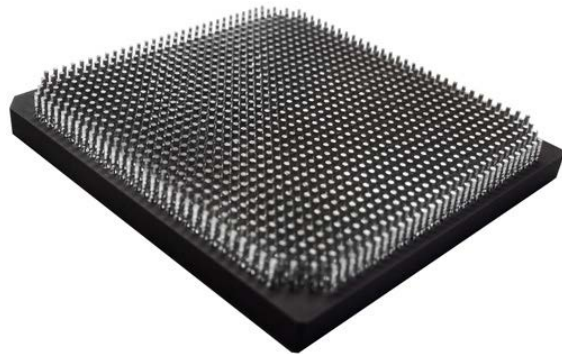
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NEPCON China Stand #1F04

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TopLine Exhibiting CCGA, Solder Joint Reliability Solutions at NEPCON China April 25 - 27

Irvine California, USA – TopLine will exhibit for the 4th straight year at NEPCON China in Shanghai, in Stand #1F04. Featured products will include CCGA - Column Grid Arrays and daisy chain BGA test vehicles. CCGA Column Grid Array IC packages are made with non-collapsible solder columns for surface mount soldering on printed circuit boards (PCBs), and provide more compliancy than solder balls (Ball Grid Arrays or BGAs) to absorb stress and increase solder joint reliability under harsh operating conditions.



NEPCON China 2017 will be held April 25 – 27 at the Shanghai World EXPO Exhibition & Convention Center. NEPCON China is a prestigious professional trade platform and exhibition on SMT (surface mount technology) and EMA (electronics manufacturing automation). It brings together over 450 renowned brands from the electronics manufacturing industry around the globe with innovative equipment, materials, and system integration solutions.

TopLine has been active in promoting its products in the China market for 20 years.

About TopLine

TopLine Corporation is a leading provider of test vehicle components and packaging solutions for Circuit Assemblies. TopLine manufactures CCGA Column Grid Arrays, solder columns, and a wide range of daisy chain semiconductor packages, and offers a complete range of daisy chain test chips for process development, experimentation, machine evaluation, solder training, and SMT assembly practice. TopLine products provide hands-on learning for engineers. TopLine is a one-stop source for all dummy components. For more information, contact TopLine Corporation, Tel (800) 776-9888; Email: sales@TopLine.tv or visit the TopLine stand, #1F04, at NEPCON China.

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